

Description

The DMP3015LSS uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



SOP-8

General Features

 $V_{DS} = -30V I_{D} = -15A$

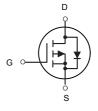
 $R_{DS(ON)}$ < 8.7m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMP3015LSS	SOP-8	HXY MOSFET	3000

Absolute Maximum Ratings (T_C=25[°]Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	-30	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-15	А	
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	10V ¹ -11		
Ірм	Pulsed Drain Current ²	sed Drain Current ² -56		
EAS	Single Pulse Avalanche Energy ³	151	mJ	
las	Avalanche Current	-55	А	
P _D @T _A =25°C	Total Power Dissipation ⁴	1.5	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
Reja	Thermal Resistance Junction-Ambient ¹(t≦10s)	40	°C/W	
	Thermal Resistance Junction-Ambient ¹	75	°C/W	
Rejc	Thermal Resistance Junction-Case ¹	24	°C/W	



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V	
△BVDSS/△TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.018		V/°C	
		V _{GS} =-10V , I _D =-12A		5.8	8.7		
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-10A		8.5	13.5	$\boldsymbol{m}\Omega$	
$V_{GS(th)}$	Gate Threshold Voltage		-1.2		-2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =-250uA		5.04		mV/°C	
la a a	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	,	
loss		V _{DS} =-24V , V _{GS} =0V , T _J =55°C			-5	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-12A		25		S	
Qg	Total Gate Charge (-4.5V)			30		nC	
Qgs	Gate-Source Charge	 V _{DS} =-15V , V _{GS} =-4.5V , I _D =-12A		10			
Q _{gd}	Gate-Drain Charge			10.4			
Td(on)	Turn-On Delay Time			9.4		ns	
Tr	Rise Time	V _{DD} =-15V , V _{GS} =-10V ,		10.2			
Td(off)	Turn-Off Delay Time	R _G =3.3 , I _D =-1A		117			
Tf	Fall Time			24			
Ciss	Input Capacitance			3448			
Coss	Output Capacitance	 V _{DS} =-15V , V _{GS} =0V , f=1MHz		508		pF	
Crss	Reverse Transfer Capacitance			421			
Is	Continuous Source Current ^{1,5}				-14	Α	
lsм	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			-56	Α	
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V	
t _{rr}	Reverse Recovery Time	IF=-10A, dI/dt=100A/µs,		19.4		nS	
Qrr	Reverse Recovery Charge	T _J =25°C		9.1		nC	

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AS} =-55A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

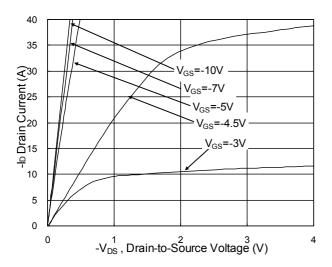


Fig.1 Typical Output Characteristics

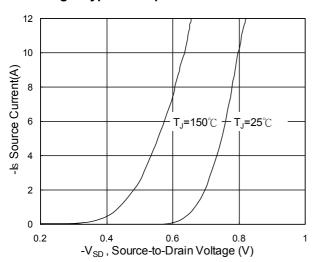


Fig.3 Forward Characteristics Of Reverse

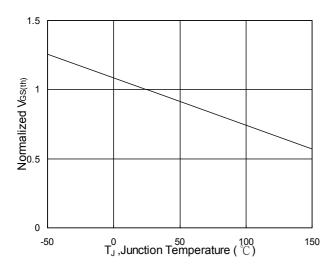


Fig.5 Normalized V_{GS(th)} vs. T_J

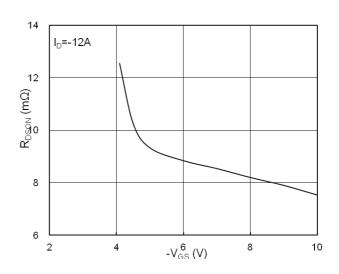


Fig.2 On-Resistance v.s Gate-Source

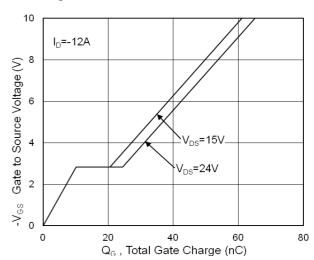


Fig.4 Gate-Charge Characteristics

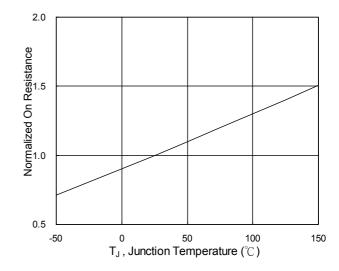
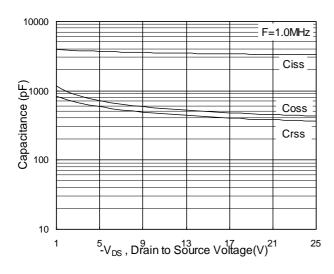


Fig.6 Normalized R_{DSON} vs. T_J





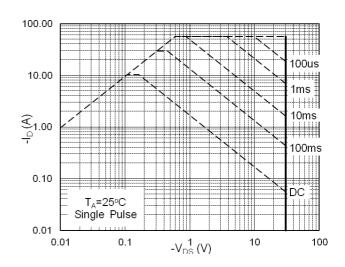


Fig.7 Capacitance

Fig.8 Safe Operating Area

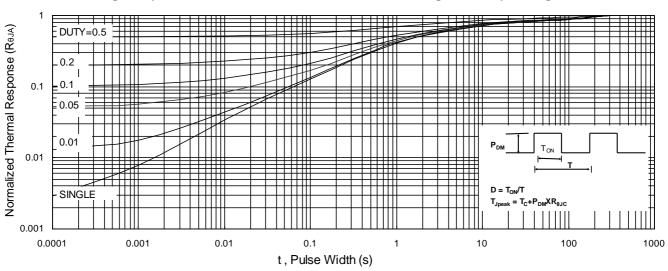


Fig.9 Normalized Maximum Transient Thermal Impedance

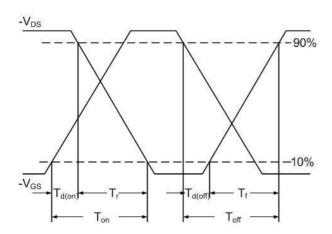


Fig.10 Switching Time Waveform

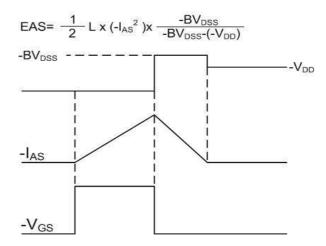
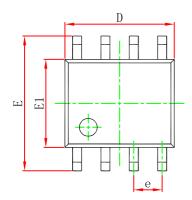
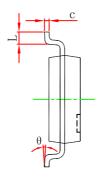


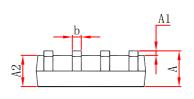
Fig.11 Unclamped Inductive Switching Waveform



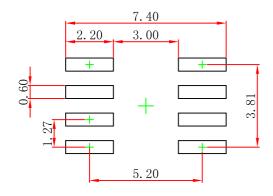
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1. 350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
c	0.170	0. 250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1. 270 (BSC)		0.050 (BSC)		
E	5.800	6. 200	0. 228	0. 244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

P-Channel Enhancement Mode MOSFET

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